

# **UPDATE CHANGE NOTIFICATION # 20102**

Generic Copy

Issue Date: 21-Jan-2014

<u>TITLE:</u> Update Change Notification to FPCN20102 for MFP10SK Products transfer from Taihei Electronics Co., Ltd to Sanyo Semiconductor Manufacturing Philippines Corporation (SSMP).

PROPOSED FIRST SHIP DATE: 16-Nov-2013

AFFECTED CHANGE CATEGORY(S): MFP10SK assembly site, facilities, materials

<u>ADDITIONAL RELIABILITY DATA:</u> Contact your local ON Semiconductor Sales Office or <a href="mailto:Satoru.Fujinuma@onsemi.com">Satoru.Fujinuma@onsemi.com</a>

<u>SAMPLES:</u> Contact your local ON Semiconductor Sales Office or <Takashi.Asami@omsemi.com>

#### FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or

- < Takashi. Nakata@onsemi.com>
- < Naoki.Koyama@onsemi.com>

### **NOTIFICATION TYPE:**

Update Change Notification to FPCN.

### **DESCRIPTION AND PURPOSE:**

FPCN20102 announced MFP10SK Products transfer from Taihei Electronics Co., Ltd to Sanyo Semiconductor Manufacturing Philippines Corporation (SSMP) on 16-Aug-2013 because Taihei Electronics Co., Ltd. closed their outsource business at the end of June 2013.

FPCN20102 also showed the reliability result of 500hr because reliability test was still in process at that time.

This update notification is to announce that the reliability evaluation result of 1000hr for the transferred products was completed and has no problem.

Equipment and materials is changed by transferring site and have proven sufficient in other packages in Sanyo Semiconductor Manufacturing Philippines Corporation (SSMP). There is no change to the package external dimensions and shipping form.

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## **RELIABILITY DATA SUMMARY:**

## **Reliability Test Results:**

Test Items	Test Conditions	Test Time	Failure
Temperature Humidity Bias ※	Ta=85degC, RH=85%,VCC=Recommended.	1000hrs	0
Temperature Cycle	Ta=-55degC, 30min⇔ Ta=150°C 30min.	200сус	0
Pressure Cooker	Ta=121degC,RH=100%,2.03x10 <sup>5</sup> Pa	200hrs	0
High Temperature Storage	Ta=150degC	1000hrs	0
Resistance to Soldering heat (Reflow Soldering)	260degC,10s	2 times	0

Notice) The test items with  $\times$  mark are put into operation after the reflow soldering (at 260°C for 10seconds).

### **ELECTRICAL CHARACTERISTIC SUMMARY:**

There is no change in the electrical performance. Datasheet specifications remain unchanged.

## **CHANGED PART IDENTIFICATION:**

Products manufactured at SSMP will be marked with 'L7' preceding the Lot No. on shipping label.

## **List of affected General Parts:**

LA6583MC-AH

LA6588MC-AH

LA6588MC-BH

LB11861MC-AH

LB1846MC-AH

LB1862MC-AH

LB1948MC-AH

LB1948MC-BH

LB1948MC-ZH

LC87F2608AUMM-AH

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Judgment Criteria: Judgment Criteria are due to the limits of the electrisitics in the detail specification.